

AMENDMENTS TO THE CLAIMS

Claims 1-21 (Cancelled).

22. (Previously presented) An apparatus for processing a substrate, comprising:

a processing head for processing the substrate by bringing the substrate into contact with a processing liquid supplied to and held in the processing head, said processing head having a substrate holder for holding the substrate, said processing head being arranged to hold the substrate with said substrate holder while a surface to be processed of the substrate is facing upwardly, and to define a processing bath for holding the processing liquid with said surface to be processed of the substrate and a seal ring for sealing an outer peripheral region of said surface to be processed of the substrate;

a heat-insulating tank surrounding said substrate holder in a water-tight manner, for holding the processing liquid held in said processing head together with said substrate holder at a predetermined temperature with a thermal medium; and

a processing liquid supplying system for supplying the processing liquid at a predetermined temperature to said processing head.

23. (Original) An apparatus according to claim 22, further comprising:

a processing liquid retrieving system for retrieving the processing liquid which has been used to process the substrate from said processing head and returning the retrieved processing liquid to said processing liquid supplying system.

Claim 24 (Cancelled).

25. (Original) An apparatus according to claim 22, further comprising:

a hot water supply tank for holding a liquid as said thermal medium, said hot water supply tank having a temperature regulator, said heat-insulating tank and said hot water supply tank being connected to each other for circulating said thermal medium therebetween.

Claim 26 (Cancelled).

27. (Previously presented) An apparatus for processing a substrate, comprising:

a processing head for processing the substrate by bringing the substrate into contact with a processing liquid supplied to and held in the processing head, said processing head having a substrate holder for holding the substrate;

a heat-insulating tank surrounding said substrate holder in a water-tight manner, for holding the processing liquid held in said processing head together with said substrate holder at a predetermined temperature with a thermal medium;

a processing liquid supplying system for supplying the processing liquid at a predetermined temperature to said processing head; and

a heating head for contacting the processing liquid held in said processing head, thereby to heat the processing liquid, wherein said heating head has a contact surface for contacting said processing liquid held in said processing head, said contact surface being tapered such that the distance between said contact surface and the surface of the processing liquid held in said processing head is progressively increased radially outwardly from the center of the contact surface.

28. (Original) An apparatus according to claim 22, wherein said processing liquid supplying system has a processing liquid supply tank for holding the processing liquid therein, said processing liquid supply tank having a temperature regulator and a stirrer for stirring the processing liquid held therein.

29. (Original) An apparatus according to claim 22, wherein said processing liquid supplying system has a processing liquid supply tank for holding the processing liquid therein, and a temperature regulating device for regulating the temperature of the processing liquid which is supplied from said processing liquid supply tank to said processing head.

30. (Original) An apparatus according to claim 23, wherein said processing liquid retrieving system has a temperature regulating device for regulating the temperature of the processing liquid which is returned from said processing head to said processing liquid supplying system.

31. (Previously presented) An apparatus for processing a substrate, comprising:
a processing head for processing the substrate by bringing the substrate into contact with a processing liquid supplied to and held in the processing head, said processing head having a substrate holder for holding the substrate;
a heat-insulating tank surrounding said substrate holder in a water-tight manner, for holding the processing liquid held in said processing head together with said substrate holder at a predetermined temperature with a thermal medium; and
a processing liquid supplying system for supplying the processing liquid at a predetermined temperature to said processing head, wherein said processing liquid supplying system has a plurality of solution supply tanks for individually holding a plurality of solutions, respectively, to be mixed into a processing liquid, said solution supply tanks having respective temperature regulators, and a plurality of mixing tanks connected to said solution supply tanks for mixing the solutions supplied respectively from said solution supply tanks into the processing liquid, said mixing tanks having respective temperature regulators.

32. (Previously presented) An apparatus for processing a substrate, comprising:
a processing head for processing the substrate by bringing the substrate into contact with a processing liquid supplied to and held in the processing head, said processing head having a substrate holder for holding the substrate;
a heat-insulating tank surrounding said substrate holder in a water-tight manner, for holding the processing liquid held in said processing head together with said substrate holder at a predetermined temperature with a thermal medium; and

a processing liquid supplying system for supplying the processing liquid at a predetermined temperature to said processing head, wherein said processing liquid supplying system has a plurality of solution supply tanks for individually holding a plurality of solutions, respectively, to be mixed into a processing liquid, and a plurality of mixing tanks connected to said solution supply tanks for mixing the solutions supplied respectively from said solution supply tanks into the processing liquid.

33. (Original) An apparatus according to claim 22, wherein said processing liquid comprises an electroless plating solution.